HISTORY

Model Name : SDM-HS75/HS75P
SERVICE MANUAL
Part No. : 9-878-333-01

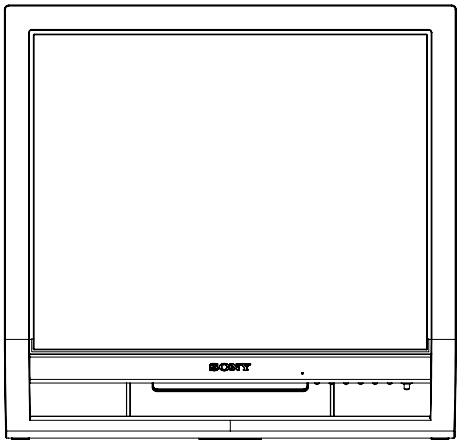
When clicking an item, it's detail is displayed.

Date	SUPP./CORR.	Description of SUP/COR	Change of main text
2005.04		NEW	–

SDM-HS75/HS75P

SERVICE MANUAL

US Model
Canadian Model
AEP Model



TFT LCD COLOR COMPUTER DISPLAY

SONY®

There are some different LCD panels are used in the model SDM-HS75/HS75P
Therefore the repair parts are also different .
Please confirm the serial number before repairing.

SDM-HS75

No.	Model name	Colour	Destination	Serial Range	Panel	Plant
	SDM-HS75	SILVER	UC	1,000,001-1,150,000	AUO	TPV
	SDM-HS75	SILVER	UC	1,150,001-1,300,000	CPT	TPV
	SDM-HS75	BLACK	UC	1,500,001-1,600,000	AUO	TPV
	SDM-HS75	BLACK	UC	1,600,001-1,700,000	CPT	TPV
	SDM-HS75	SILVER	AEP	1,000,001-1,150,000	AUO	TPV
	SDM-HS75	SILVER	AEP	1,150,001-1,300,000	CPT	TPV
	SDM-HS75	BLACK	AEP	1,500,001-1,600,000	AUO	TPV
	SDM-HS75	BLACK	AEP	1,600,001-1,700,000	CPT	TPV

SDM-HS75P

No.	Model name	Colour	Destination	Serial Range	Panel	Plant
	SDM-HS75P	SILVER	UC	1,000,001-1,150,000	AUO	TPV
	SDM-HS75P	SILVER	UC	1,150,001-1,300,000	CPT	TPV
	SDM-HS75P	BLACK	UC	1,500,001-1,600,000	AUO	TPV
	SDM-HS75P	BLACK	UC	1,600,001-1,700,000	CPT	TPV
	SDM-HS75P	SILVER	AEP	1,000,001-1,150,000	AUO	TPV
	SDM-HS75P	SILVER	AEP	1,150,001-1,300,000	CPT	TPV
	SDM-HS75P	BLACK	AEP	1,500,001-1,600,000	AUO	TPV
	SDM-HS75P	BLACK	AEP	1,600,001-1,700,000	CPT	TPV

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SPECIFICATIONS

1. LCD CHARACTERISTICS

Type	: TFT Color LCD Module
Active Display Area	: 17 inch(358.5(H) x 296.5(V))
Size	: 358.5(W) x 296.5(H) x 17.0(D)
Pixel Pitch	: 0.264(per one friad) x 0.264
Color Depth	: 16.2M Colors
Electrical Interface	: LVDS
Surface Treatment	: Glare

2. OPTICAL CHARACTERISTICS

2-1. Viewing Angle by Contrast Ratio 10

Right : +60°(Min.), +70°(TYP) Left : +60°(Min.), +70°(TYP)
Top :+65° min., +75°(Typ) Bottom : +55°min., +65°(Typ)

2-2. Luminance : 350(Typ)

2-3. Contrast Ratio : 450(Typ)

3. SIGNAL (Refer to the Timing Chart)

3-1. Sync Signal
- Type : Separate Sync

3-2. Video Input Signal
1) Type : R, G, B Analog
2) Voltage Level : 0~0.70 V(±5%)
3) Input Impedance : 75

3-3. Operating Frequency
Horizontal(Analog) : 28 ~ 80kHz
Horizontal(Digital) : 28 ~ 64kHz
Vertical(Analog) : 48 ~ 75Hz
Vertical(Digital) : 60Hz

4. Max. Resolution
Analog : 1280 x 1024 / 75Hz
Digital : 1280 x 1024 / 60Hz

5. POWER SUPPLY

5-1. Power : AC 100~240V, 50/60Hz , 1.0A

5-2. Power Consumption

MODE	H/V SYNC	VIDEO	POWER CONSUMPTION	LED COLOR
POWER ON (NORMAL)	ON/ON	ACTIVE	less than 45 W	GREEN
STAND-BY	OFF/ON	OFF	less than 1 W	AMBER
SUSPEND	ON/OFF	OFF	less than 1 W	AMBER
DPMS OFF	OFF/OFF	OFF	less than 1 W	AMBER
POWER S/W OFF	-	-	less than 1 W	OFF

6. ENVIRONMENT

6-1. Operating Temperature : 5°C~35°C (41°F~95°F)
(Ambient)
6-2. Relative Humidity : 10%~80% (Non-condensing)

7. DIMENSIONS (with TILT/SWIVEL)

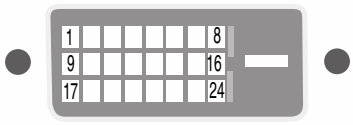
Width : 388 mm
Depth : 104 mm
Height : 397 mm

8. WEIGHT (with TILT/SWIVEL)

Net. Weight : 4.9 kg
Gross Weight : 7.3 kg

Signal Connector Pin Assignment

• DVI-D Connector



Pin	Signal (DVI-D)	Pin	Signal (DVI-D)
1	T. M. D. S. Data2-	16	Hot Plug Detect
2	T. M. D. S. Data2+	17	T. M. D. S. Data0-
3	T. M. D. S. Data2/4 Shield	18	T. M. D. S. Data0+
4	T. M. D. S. Data4-	19	T. M. D. S. Data0/5 Shield
5	T. M. D. S. Data4+	20	T. M. D. S. Data5-
6	DDC Clock	21	T. M. D. S. Data5+
7	DDC Data	22	T. M. D. S. Clock Shield
8	Analog Vertical Sync.	23	T. M. D. S. Clock+
9	T. M. D. S. Data1-	24	T. M. D. S. Clock-
10	T. M. D. S. Data1+		
11	T. M. D. S. Data1/3 Shield		
12	T. M. D. S. Data3-		
13	T. M. D. S. Data3+		
14	+5V Power		
15	Ground (return for +5V, H. Sync. and V. Sync.)		

T. M. D. S. (Transition Minimized Differential Signaling)

PRECAUTION

WARNING FOR THE SAFETY-RELATED COMPONENT.

- There are some special components used in LCD monitor that are important for safety. ***These parts are marked ⚠ on the schematic diagram and the replacement parts list.*** It is essential that these critical parts should be replaced with the manufacturer's specified parts to prevent electric shock, fire or other hazard.
- Do not modify original design without obtaining written permission from manufacturer or you will void the original parts and labor guarantee.

TAKE CARE DURING HANDLING THE LCD MODULE WITH BACKLIGHT UNIT.

- Must mount the module using mounting holes arranged in four corners.
- Do not press on the panel, edge of the frame strongly or electric shock as this will result in damage to the screen.
- Do not scratch or press on the panel with any sharp objects, such as pencil or pen as this may result in damage to the panel.
- Protect the module from the ESD as it may damage the electronic circuit (C-MOS).
- Make certain that treatment person's body are grounded through wrist band.
- Do not leave the module in high temperature and in areas of high humidity for a long time.
- The module not be exposed to the direct sunlight.
- Avoid contact with water as it may a short circuit within the module.
- If the surface of panel become dirty, please wipe it off with a softmaterial. (Cleaning with a dirty or rough cloth may damage the panel.)

⚠ CAUTION

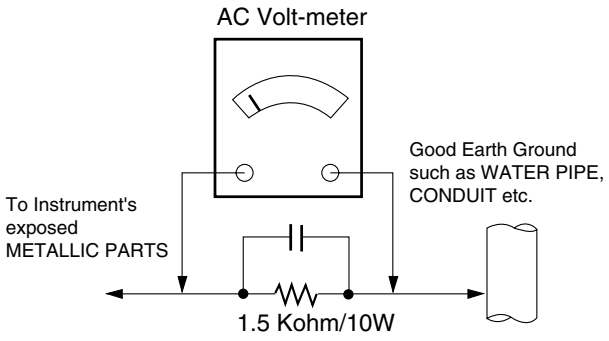
Please use only a plastic screwdriver to protect yourself from shock hazard during service operation.

⚠ WARNING

BE CAREFUL ELECTRIC SHOCK !

- If you want to replace with the new backlight (CCFL) or inverter circuit, must disconnect the AC adapter because high voltage appears at inverter circuit about 650Vrms.
- Handle with care wires or connectors of the inverter circuit. If the wires are pressed cause short and may burn or take fire.

Leakage Current Hot Check Circuit



SERVICING PRECAUTIONS

CAUTION: Before servicing receivers covered by this service manual and its supplements and addenda, read and follow the ***SAFETY PRECAUTIONS*** on page 3 of this publication.

NOTE: If unforeseen circumstances create conflict between the following servicing precautions and any of the safety precautions on page 3 of this publication, always follow the safety precautions. Remember: Safety First.

General Servicing Precautions

1. Always unplug the receiver AC power cord from the AC power source before;
   a. Removing or reinstalling any component, circuit board module or any other receiver assembly.
   b. Disconnecting or reconnecting any receiver electrical plug or other electrical connection.
   c. Connecting a test substitute in parallel with an electrolytic capacitor in the receiver.
      CAUTION: A wrong part substitution or incorrect polarity installation of electrolytic capacitors may result in an explosion hazard.
   d. Discharging the picture tube anode.
2. Test high voltage only by measuring it with an appropriate high voltage meter or other voltage measuring device (DVM, FETVOM, etc) equipped with a suitable high voltage probe.
   Do not test high voltage by "drawing an arc".
3. Discharge the picture tube anode only by (a) first connecting one end of an insulated clip lead to the degaussing or kine aquadag grounding system shield at the point where the picture tube socket ground lead is connected, and then (b) touch the other end of the insulated clip lead to the picture tube anode button, using an insulating handle to avoid personal contact with high voltage.
4. Do not spray chemicals on or near this receiver or any of its assemblies.
5. Unless specified otherwise in this service manual, clean electrical contacts only by applying the following mixture to the contacts with a pipe cleaner, cotton-tipped stick or comparable non-abrasive applicator; 10% (by volume) Acetone and 90% (by volume) isopropyl alcohol (90%-99% strength)
   CAUTION: This is a flammable mixture.
   Unless specified otherwise in this service manual, lubrication of contacts in not required.
6. Do not defeat any plug/socket B+ voltage interlocks with which receivers covered by this service manual might be equipped.
7. Do not apply AC power to this instrument and/or any of its electrical assemblies unless all solid-state device heat sinks are correctly installed.
8. Always connect the test receiver ground lead to the receiver chassis ground before connecting the test receiver positive lead.
   Always remove the test receiver ground lead last.
9. *Use with this receiver only the test fixtures specified in this service manual.*
   CAUTION: Do not connect the test fixture ground strap to any heat sink in this receiver.

Electrostatically Sensitive (ES) Devices

Some semiconductor (solid-state) devices can be damaged easily by static electricity. Such components commonly are called *Electrostatically Sensitive (ES) Devices.* Examples of typical ES devices are integrated circuits and some field-effect transistors and semiconductor "chip" components. The following techniques should be used to help reduce the incidence of component damage caused by static by static electricity.

1. Immediately before handling any semiconductor component or semiconductor-equipped assembly, drain off any electrostatic charge on your body by touching a known earth ground. Alternatively, obtain and wear a commercially available discharging wrist strap device, which should be removed to prevent potential shock reasons prior to applying power to the unit under test.
2. After removing an electrical assembly equipped with ES devices, place the assembly on a conductive surface such as aluminum foil, to prevent electrostatic charge buildup or exposure of the assembly.
3. Use only a grounded-tip soldering iron to solder or unsolder ES devices.
4. Use only an anti-static type solder removal device. Some solder removal devices not classified as "anti-static" can generate electrical charges sufficient to damage ES devices.
5. Do not use freon-propelled chemicals. These can generate electrical charges sufficient to damage ES devices.
6. Do not remove a replacement ES device from its protective package until immediately before you are ready to install it. (Most replacement ES devices are packaged with leads electrically shorted together by conductive foam, aluminum foil or comparable conductive material).
7. Immediately before removing the protective material from the leads of a replacement ES device, touch the protective material to the chassis or circuit assembly into which the device will be installed.
   CAUTION: Be sure no power is applied to the chassis or circuit, and observe all other safety precautions.
8. Minimize bodily motions when handling unpackaged replacement ES devices. (Otherwise harmless motion such as the brushing together of your clothes fabric or the lifting of your foot from a carpeted floor can generate static electricity sufficient to damage an ES device.)

General Soldering Guidelines

1. Use a grounded-tip, low-wattage soldering iron and appropriate tip size and shape that will maintain tip temperature within the range or 500ΩF to 600ΩF.
2. Use an appropriate gauge of RMA resin-core solder composed of 60 parts tin/40 parts lead.
3. Keep the soldering iron tip clean and well tinned.
4. Thoroughly clean the surfaces to be soldered. Use a mall wire-bristle (0.5 inch, or 1.25cm) brush with a metal handle.
   Do not use freon-propelled spray-on cleaners.
5. Use the following unsoldering technique
   a. Allow the soldering iron tip to reach normal temperature.
      (500ΩF to 600ΩF)
   b. Heat the component lead until the solder melts.
   c. Quickly draw the melted solder with an anti-static, suction-type solder removal device or with solder braid.
      CAUTION: Work quickly to avoid overheating the circuitboard printed foil.
6. Use the following soldering technique.
   a. Allow the soldering iron tip to reach a normal temperature (500ΩF to 600ΩF)
   b. First, hold the soldering iron tip and solder the strand against the component lead until the solder melts.
   c. Quickly move the soldering iron tip to the junction of the component lead and the printed circuit foil, and hold it there only until the solder flows onto and around both the component lead and the foil.
      CAUTION: Work quickly to avoid overheating the circuit board printed foil.
   d. Closely inspect the solder area and remove any excess or splashed solder with a small wire-bristle brush.

IC Remove/Replacement

Some chassis circuit boards have slotted holes (oblong) through which the IC leads are inserted and then bent flat against the circuit foil. When holes are the slotted type, the following technique should be used to remove and replace the IC. When working with boards using the familiar round hole, use the standard technique as outlined in paragraphs 5 and 6 above.

Removal

1. Desolder and straighten each IC lead in one operation by gently prying up on the lead with the soldering iron tip as the solder melts.
2. Draw away the melted solder with an anti-static suction-type solder removal device (or with solder braid) before removing the IC.

Replacement

1. Carefully insert the replacement IC in the circuit board.
2. Carefully bend each IC lead against the circuit foil pad and solder it.
3. Clean the soldered areas with a small wire-bristle brush. (It is not necessary to reapply acrylic coating to the areas).

"Small-Signal" Discrete Transistor Removal/Replacement

1. Remove the defective transistor by clipping its leads as close as possible to the component body.
2. Bend into a "U" shape the end of each of three leads remaining on the circuit board.
3. Bend into a "U" shape the replacement transistor leads.
4. Connect the replacement transistor leads to the corresponding leads extending from the circuit board and crimp the "U" with long nose pliers to insure metal to metal contact then solder each connection.

Power Output, Transistor Device Removal/Replacement

1. Heat and remove all solder from around the transistor leads.
2. Remove the heat sink mounting screw (if so equipped).
3. Carefully remove the transistor from the heat sink of the circuit board.
4. Insert new transistor in the circuit board.
5. Solder each transistor lead, and clip off excess lead.
6. Replace heat sink.

Diode Removal/Replacement

1. Remove defective diode by clipping its leads as close as possible to diode body.
2. Bend the two remaining leads perpendicular y to the circuit board.
3. Observing diode polarity, wrap each lead of the new diode around the corresponding lead on the circuit board.
4. Securely crimp each connection and solder it.
5. Inspect (on the circuit board copper side) the solder joints of the two "original" leads. If they are not shiny, reheat them and if necessary, apply additional solder.

Fuse and Conventional Resistor Removal/Replacement

1. Clip each fuse or resistor lead at top of the circuit board hollow stake.
2. Securely crimp the leads of replacement component around notch at stake top.
3. Solder the connections.
   CAUTION: Maintain original spacing between the replaced component and adjacent components and the circuit board to prevent excessive component temperatures.

Circuit Board Foil Repair

Excessive heat applied to the copper foil of any printed circuit board will weaken the adhesive that bonds the foil to the circuit board causing the foil to separate from or "lift-off" the board. The following guidelines and procedures should be followed whenever this condition is encountered.

At IC Connections

To repair a defective copper pattern at IC connections use the following procedure to install a jumper wire on the copper pattern side of the circuit board. (Use this technique only on IC connections).

1. Carefully remove the damaged copper pattern with a sharp knife. (Remove only as much copper as absolutely necessary).
2. carefully scratch away the solder resist and acrylic coating (if used) from the end of the remaining copper pattern.
3. Bend a small "U" in one end of a small gauge jumper wire and carefully crimp it around the IC pin. Solder the IC connection.
4. Route the jumper wire along the path of the out-away copper pattern and let it overlap the previously scraped end of the good copper pattern. Solder the overlapped area and clip off any excess jumper wire.

At Other Connections

Use the following technique to repair the defective copper pattern at connections other than IC Pins. This technique involves the installation of a jumper wire on the component side of the circuit board.

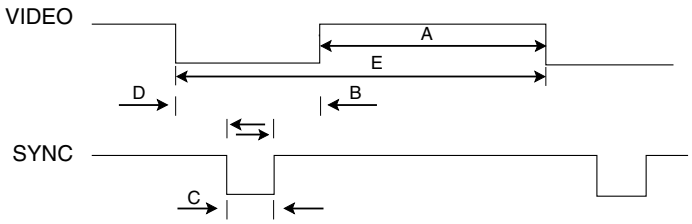
1. Remove the defective copper pattern with a sharp knife.
   Remove at least 1/4 inch of copper, to ensure that a hazardous condition will not exist if the jumper wire opens.
2. Trace along the copper pattern from both sides of the pattern break and locate the nearest component that is directly connected to the affected copper pattern.
3. Connect insulated 20-gauge jumper wire from the lead of the nearest component on one side of the pattern break to the lead of the nearest component on the other side.
   Carefully crimp and solder the connections.
   CAUTION: Be sure the insulated jumper wire is dressed so the it does not touch components or sharp edges.

TIMING CHART

<< Dot Clock **(MHz),** Horizontal Frequency **(kHz)**, Vertical Frequency **(Hz)**, Horizontal etc... **(μs)**, Vertical etc... **(ms)** >>

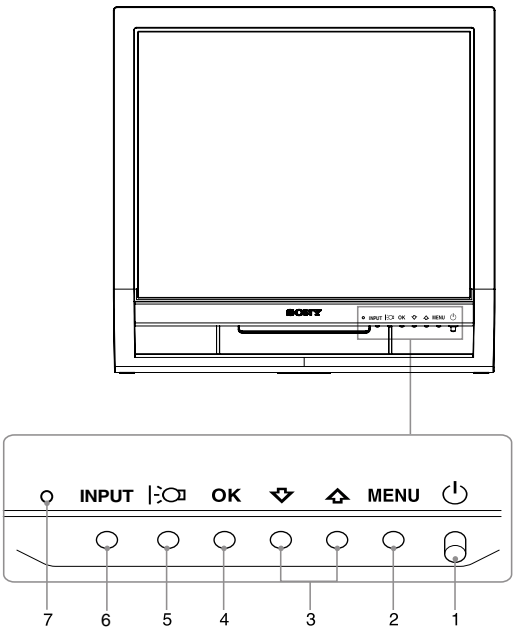
Mode	H/V Sort	Sync Polarity	Dot Clock	Frequency	Total Period (E)	Video Active Time (A)	Blanking time (B)	Sync Duration (D)	Back Porch (F)	Front Porch (C)	Resolution
1	H	-	28.350	31.50 KHz	900	720	180	108	54	18	720 x 400
	V	+		70.156 Hz	449	400	49	3	34	12	
2	H	-	25.175	31.469KHz	800	640	160	96	48	16	640 x 480
	V	-		59.940 Hz	525	480	45	2	33	10	
3	H	-	30.240	35.00 KHz	864	640	224	64	96	64	640 x 480
	V	-		66.667 Hz	525	480	45	3	39	3	
4	H	-	31.500	37.50KHz	840	640	200	64	120	16	640 x 480
	V	-		75.0 Hz	500	480	20	3	16	1	
5	H	-	31.505	35.162 KHz	896	720	176	40	102	34	720 x 480
	V	-		59.901 Hz	587	480	107	2	93	12	
6	H	+-	36.0	35.156 KHz	1024	800	224	72	128	24	800 x 600
	V	+		56.25 Hz	625	600	25	2	22	1	
7	H	+	40.0	37.879 KHz	1056	800	256	128	88	40	800 x 600
	V	+		60.317 Hz	628	600	28	4	23	1	
8	H	+	50.0	48.077 KHz	1040	800	240	120	64	56	800 x 600
	V	+		72.188 Hz	666	600	66	6	23	37	
9	H	+	49.5	46.875 KHz	1056	800	256	80	160	16	800 x 600
	V	+		75.0 Hz	625	600	25	3	21	1	
10	H	-	57.285	49.727 KHz	1152	832	320	64	224	32	832 x 624
	V	-		74.553 Hz	667	624	43	3	37	3	(MAC16")
11	H	-	65	48.363 KHz	1344	1024	320	136	160	24	1024 x 768
	V	-		60.004 Hz	806	768	38	6	29	3	
12	H	-	75	56.476 KHz	1328	1024	304	136	144	24	1024 x 768
	V	-		70.069 Hz	806	768	38	6	29	3	
13	H	+	78.75	60.023 KHz	1312	1024	288	96	176	16	1024 x 768
	V	+		75.029 Hz	800	768	32	3	28	1	
14	H	-	80.00	60.241 KHz	1328	1024	304	96	176	32	1024 x 768
	V	-		74.927 Hz	804	768	36	3	30	3	(MAC 19)
15	H	+	108	67.500 KHz	1600	1152	448	128	256	64	1152 x 864
	V	+		75.000 Hz	900	864	36	3	32	1	
16	H	-	100	68.681 KHz	1456	1152	304	128	144	32	1152 x 870
	V	-		75.062 Hz	915	870	45	3	39	3	(MAC 21)
17	H	-	92.940	61.795 KHz	1504	1152	352	128	194	30	1152 x 900
	V	-		65.950 Hz	937	900	37	4	31	2	
18	H	-	105.590	71.732 KHz	1472	1152	320	96	208	16	1152 x 900
	V	-		76.068 Hz	943	900	43	8	33	2	
19	H	+	46.200	31.216 KHz	1480	1170	310	129	144	37	1170 x 584
	V	+		50.026 Hz	624	584	40	3	34	3	
20	H	+	108.00	60.000 KHz	1800	1280	520	112	312	96	1280 x 960
	V	+		60.000 Hz	1000	960	40	3	36	1	
21	H	+	108.00	63.981 KHz	1688	1280	408	112	248	48	1280 x1024
	V	+		60.020 Hz	1066	1024	42	3	38	1	
22	H	+	135	79.976 KHz	1688	1280	408	144	248	16	1280 x 1024
	V	+		75.025 Hz	1066	1024	42	3	38	1	

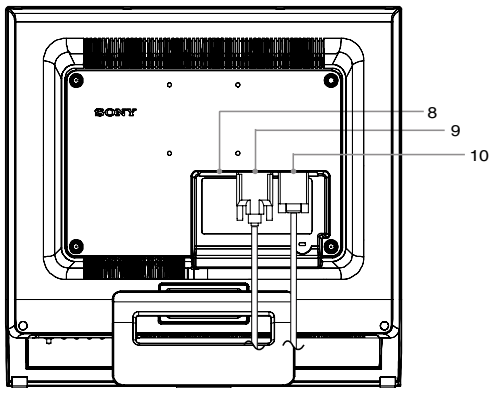
TIMING CHART



OPERATING INSTRUCTIONS

FRONT / REAR VIEW





1. ⏻ (Power) switch and indicator
To turn the display on or off, press the ⏻ (power) switch upward.
The power indicator lights up in green when the display is turned on, and lights up in orange when the monitor is in power saving mode.

2. MENU button
This button displays or closes the main menu.

3. ↑/↓ buttons
These buttons function as the ↑/↓ buttons when selecting the menu items and making adjustments.

4. OK button
This button selects the item or executes the settings in the menu.

5. ☼ button
This button is used to change the brightness of the screen.

6. INPUT button
This button switches the video input signal between INPUT1 and INPUT2 when computers are connected to the moniter.

7. Light sensor
This sensor measures the brightness of the surrounding area. Be sure not to cover the sensor with papers, etc.

8. AC IN connector
Connect the power cord(supplied).

9. DVI-D input connector (digital RGB)
This connector inputs digital RGB video signals that comply with DVI Rev.1.0.

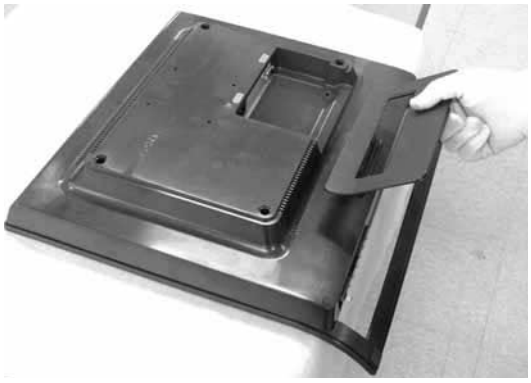
10. HD15 (RGB) input connector (analog RGB)
This connector inputs analog RGB video signals (0.7 Vp-p, positive) and SYNC signals. DDC (Display Data Channel) is a standard of VESA.

DISASSEMBLY

 # 1

1) Please remove Screws which are between Hinge and Stand support like picture.

 # 2

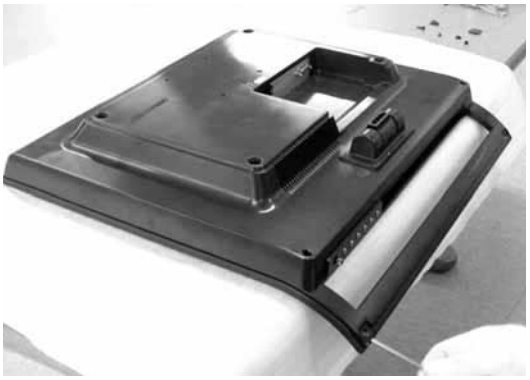


2) Please pull the Stand support at the Hinge, then Stand support will be departed.

 # 3

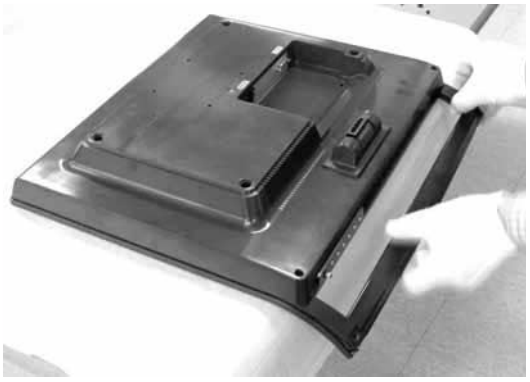
3) Please remove the screw cover at the Back cabinet, then screw cover will be departed.

 # 4



4) Please lift the left-bottom side edge of Back cabinet with tip-jig like picture, then latch will be departed.

 # 5



5) Please lift the bottom side of Back cabinet with fingertip like picture, then latch will be departed.

 # 6

6) Please pull the left side of Back cabinet like picture then latch will be departed.

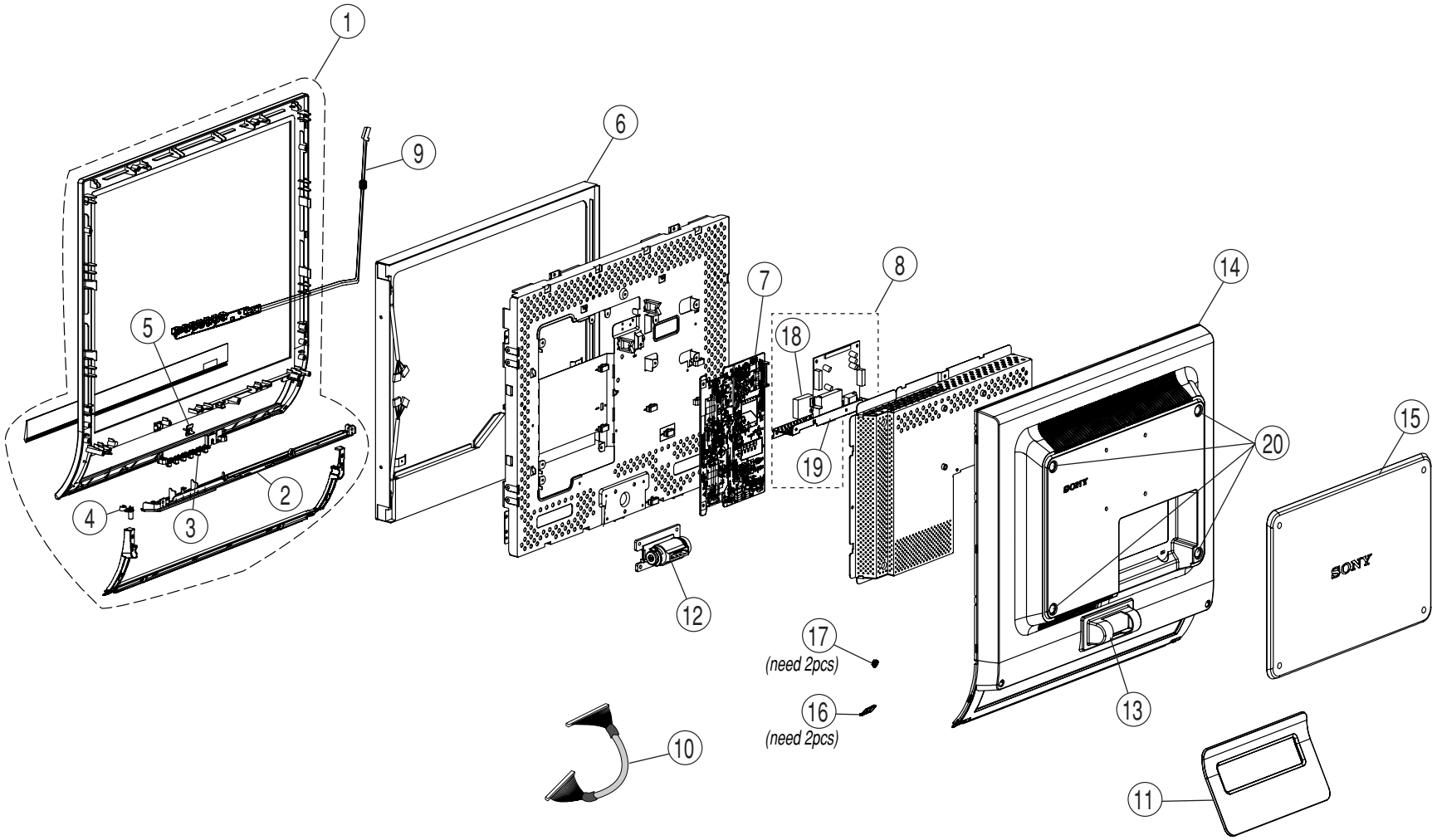
 # 7

7) If Back cabinet will be departed easily, please pull bottom side of Back cabinet faced hinge outside.

 # 8

8) If Back cabinet will be departed easily, please pull upside edge of Back cabinet outside.

EXPLODED VIEW



EXPLODED VIEW PARTS LIST

Plant: TPV SDM-HS75

Ref. No.	SONY Part No.	SONY name
1	X-2050-739-1	BEZEL ASSY (Silver)
	X-2050-831-1	BEZEL ASSY (Black)
2	2-588-886-01	BUTTON BRAKET
3	2-588-883-01	MULTI BUTTON
4	2-588-884-01	POWER BUTTON
6	1-805-828-11	LCD PANEL (CPT)
	1-805-883-11	LCD PANEL (CMO)
7	1-789-176-11	MOUNTED PWB, G
8	1-789-175-11	MOUNTED PWB, A
9	1-789-177-11	MOUNTED PWB, H
10	1-900-283-15	CONNECTOR ASSY
11	X-2050-743-1	STAND ASSY
12	X-2050-745-1	HINGE ASSY
13	2-588-881-01	HINGE COVER
14	X-2050-741-1	BACK CABINET ASSY
15	2-588-882-01	REAR COVER (Silver)
	2-588-882-11	REAR COVER (Black)
16	2-591-630-01	RUBBER FOOT
17	2-591-629-01	SCREW COVER
18	1-819-429-11	AC INLET
19	2-588-887-01	METAL BRAKET
20	2-593-158-01	RUBBER BUSHING
		ACCESSORIES & PACKING MATERIALS
21	1-829-848-11	POWER CORD, BLACK (U/C)
	1-829-849-11	POWER CORD, BLACK (AEP)
22	1-829-876-11	D-SUB CABLE
24	2-583-749-01	QUICK SETUP GUIDE (U/C)
	2-583-749-11	QUICK SETUP GUIDE (AEP)
25	2-149-411-08	CD-ROM

EXPLODED VIEW PARTS LIST

Plant: TPV SDM-HS75P

Ref. No.	SONY Part No.	SONY name
1	X-2050-740-1	BEZEL ASSY (Silver)
	X-2050-832-1	BEZEL ASSY (Black)
2	2-588-886-11	BUTTON BRAKET
3	2-588-883-11	MULTI BUTTON
4	2-588-884-01	POWER BUTTON
5	2-588-885-01	LIGHT FILTER
6	1-805-827-11	LCD PANEL (AUO)
7	1-789-184-11	MOUNTED PWB, G (AUO)
8	1-789-185-11	MOUNTED PWB, A (AUO)
9	1-789-186-11	MOUNTED PWB, H (AUO)
10	1-900-283-15	CONNECTOR ASSY
11	X-2050-743-1	STAND ASSY
12	X-2050-745-1	HINGE ASSY
13	2-588-881-01	HINGE COVER
14	X-2050-742-1	BACK CABINET ASSY
15	2-588-882-01	REAR COVER (Silver)
	2-588-882-11	REAR COVER (Black)
16	2-591-630-01	RUBBER FOOT
17	2-591-629-01	SCREW COVER
18	1-819-429-11	AC INLET
19	2-588-887-01	METAL BRAKET
20	2-593-158-01	RUBBER BUSHING
ACCESSORIES & PACKING MATERIALS		
21	1-829-848-11	POWER CORD, BLACK (U/C)
	1-829-849-11	POWER CORD, BLACK (AEP)
22	1-829-876-11	D-SUB CABLE
23	1-829-855-11	DVI CABLE
24	2-583-750-01	QUICK SETUP GUIDE (U/C)
	2-583-750-11	QUICK SETUP GUIDE (AEP)
25	2-149-411-08	CD-ROM

EXPLODED VIEW PARTS LIST

Plant: LGE SDM-HS75P

Ref. No.	SONY Part No.	SONY name
1	X-2059-782-1	BEZEL ASSY (Black)
2	2-629-791-01	BUTTON BRAKET
3	2-588-343-01	MULTI BUTTON
4	2-588-344-01	POWER BUTTON
5		LCD PANEL ( )
		LCD PANEL ( )
7	1-789-179-11	MOUNTED PWB, G
8	1-789-190-11	MOUNTED PWB, A
9	1-789-191-11	MOUNTED PWB, H
10	1-900-275-71	CONNECTOR ASSY
11	X-2055-947-1	STAND ASSY
12	X-2055-948-1	HINGE ASSY
14	X-2059-812-1	BACK CABINET ASSY
15		REAR COVER ( )
	2-629-863-11	REAR COVER (Black)
16	2-591-628-01	FRONT FOOT RUBBER
17	2-591-627-01	SCREW COVER
18	1-819-276-11	AC INLET
19	2-629-792-01	METAL BRAKET
20	2-593-157-01	RUBBER BUSHING
ACCESSORIES & PACKING MATERIALS		
21	1-827-118-11	POWER-SUPPLY CORD SET (U/C), Black
22	1-827-757-11	D-SUB CABLE
24	2-589-530-01	QUICK SETUP GUIDE (U/C)
25	2-633-911-01	CD-ROM